# Aligned Carbon Nanofibre-Polymer Composite Membranes

# **CNT Growth and Manipulation**







#### Eleanor Campbell Dept. of Physics, Göteborg University

Plasma CVD Growth –
 Polymer/Nanofibre Composite

Low ambient temperature growth

 Dielectrophoretic separation of metallic and semiconducting SWNT & its use in device fabrication (if time)

# Plasma CVD Growth of Nanotubes /fibres

T = 700 °C Ni catalyst Fe catalyst

### $C_2H_2:NH_3 = 1:5$ , 4 Torr tip-grown fibres $C_2H_2:H_2 = 1:3$ 7 Torr base-grown MWNT



#### Growth Quality depends critically on Plasma Current Density



Array growth on Mo substrate

 $C_2H_2:NH_3 = 1:5$ 

Kabir et al., Nanotech. **16** (2005) 458 Kabir et al., Nanotech**. 17** (2006) 790





Optical spectroscopy shows the relative decrease in molecular/atomic precursors and also a clear increase in CN intensity beyond 30 mA (4.5 mA/cm<sup>2</sup>)

- Onset of non-catalytic deposition and increased sputtering

M. Jönsson

#### **B.** Gindre



Can these vertically aligned CNF be used to make an anistropically conducting polymer membrane?



Diameter ca. 50 nm

#### Polymer – CNT Composite Materials



Array of individual nanotubes grown on a Mo substrate

Arrays after spin-coating showing photonic-crystal effects

1 cm



Morjan, Gromov, Gindre

# **Electrical Characterisation**

Two probe measurements (-5;+5)V
Deposition of gold electrodes by metal evaporation with a mask
(0.5mm in diameter and 2mm apart)

**Substrate** 

PSTACNE

Mo & Mo

layer







Au

Measured resistance through film without fibre i.e. Polystyrene alone (3  $\mu m$  thick): 10<sup>4</sup>  $\Omega$ 

With CNF: 50  $\Omega$ 

There are approximately 45000 nanofibres contacted for each measurement

-The average resistance per fibre is ca. 200-300 k $\Omega$  (compares with ca. 100 k $\Omega$  for individual fibres with 0.5 mA current carrying capacity)

#### Removing the polymer from the substrate





Leave for a couple of days



How to reduce the chip temperature to make good quality CNT at temperatures lower than 450 °C (CMOS compatibility)?



Use very local resistive heating only where you want the nanotube(s) to grow.

Mo Electrodes with narrow resistive bridge. Catalyst deposited on bridge  $(5nm Al_2O_3, 1 nm Fe)$ 14 mA, 2V for heating

Dittmer et al., Appl. Phys. A in press



#### Room Temperature Growth: MWNT



Position [um]

 $C_2H_2:H_2:Ar = 10$  sccm: 300 sccm: 500 sccm

Dittmer et al., Appl. Phys. A, in press





#### Growth stops when temperature falls below ca. 500 °C

### Thanks to:

Array Growth and Membranes:

Oleg Nerushev Raluca Morjan Martin Jönsson Baptiste Gindre Andrei Gromov Shafiq Kabir Nanorelay: SangWook Lee Anders Eriksson Jari Kinaret et al (theory)

Dielectrophoretic Separation: Andrei Gromov Low Temperature Growth: Staffan Dittmer Oleg Nerushev AC Dielectrophoresis for separating metallic and semiconducting nanotubes

$$\vec{F} \propto \varepsilon_1 \operatorname{Re}(\frac{\varepsilon_2^* - \varepsilon_1^*}{\varepsilon_2^* + 2\varepsilon_1^*}) \nabla \left| \vec{E} \right|^2$$
 2: nanotube  
1: solvent

For semiconducting SWNT F is negative, for metallic SWNT the force is positive, attracting the CNT to the electrodes. (Krupke et al)

In this way metallic nanotubes can be preferentially attracted to electrodes leaving proportionately more semiconducting SWNT in dispersion.





D.S. Lee, et al., Appl. Phys. A 80 (2005), 5

#### Nanotubes left in dispersion after deposition cycles





#### Number of Deposition Cycles

D.S. Lee, et al., Appl. Phys. A 80 (2005), 5



#### Laminar flow – no mixing of liquids



Although the interaction time is very short we get a significant increase in metallic content of lower channel on a single pass



#### Still problem with bundle formation

# **Carbon Nanotube Nanorelay**



high Q oscillator, logical switch, bistable memory element, Mechanical resonance frequency in GHz range, switching speed could be faster. J. Kinaret et al. (S. Viefers), Appl. Phys. Lett. 82, 1287 (2003) L.M. Jonsson et al., J. Appl. Phys. 96, 629 (2004)

#### Nanorelay Fabrication



Acid free method to make suspended structure: S. W. Lee et. al Appl. Phys. A 78, 283 (2004)



Axelsson et al., New J. Phys 7 (2005) 245

# $I_{source-drain}$ vs Gate Voltage, $V_{SD} = 0.5$ V

